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- Organization . . . 131 072 by 8 Bits
- Single 5-V Power Supply
- Operationally Compatible With Existing Megabit EPROMs
- Industry Standard 32-Pin Dual-In-line Package and 32-Lead Plastic Leaded Chip Carrier
- All Inputs/Outputs Fully TTL Compatible
- Maximum Access/Minimum Cycle Time

V_{CC} ± 10% '27C/PC010A-10 100 ns '27C/PC010A-12 120 ns '27C/PC010A-15 150 ns '27C/PC010A-20 200 ns

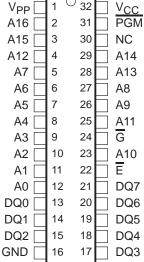
- 8-Bit Output For Use in Microprocessor-Based Systems
- Very High-Speed SNAP! Pulse Programming
- Power-Saving CMOS Technology
- 3-State Output Buffers
- 400-mV Minimum DC Noise Immunity With Standard TTL Loads
- Latchup Immunity of 250 mA on All Input and Output Pins
- No Pullup Resistors Required
- Low Power Dissipation (V_{CC} = 5.5 V)
 - Active . . . 165 mW Worst Case
 - Standby . . . 0.55 mW Worst Case (CMOS-Input Levels)
- Temperature Range Options

description

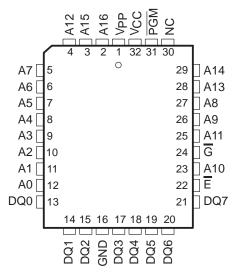
The TMS27C010A series are 131072 by 8-bit (1048576-bit), ultraviolet (UV) light erasable, electrically programmable read-only memories (EPROMs).

The TMS27PC010A series are 131072 by 8-bit (1048576-bit), one-time programmable (OTP) electrically programmable read-only memories (PROMs).





FM PACKAGE (TOP VIEW)



PIN NOMENCLATURE					
A0-A16 DQ0-DQ7 E G GND NC PGM VCC VPP	Address Inputs Inputs (programming)/Outputs Chip Enable Output Enable Ground No Internal Connection Program 5-V Power Supply 13-V Power Supply†				

[†]Only in program mode



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description (continued)

These devices are fabricated using power-saving CMOS technology for high speed and simple interface with MOS and bipolar circuits. All inputs (including program data inputs) can be driven by Series 74 TTL circuits without the use of external pullup resistors. Each output can drive one Series 74 TTL circuit without external resistors.

The TMS27C010A EPROM is offered in a dual-in-line ceramic package (J suffix) designed for insertion in mounting hole rows on 15,2-mm (600-mil) centers. The TMS27C010A is also offered with two choices of temperature ranges, 0°C to 70°C (JL suffix) and -40°C to 85°C (JE suffix). See Table 1.

The TMS27PC010A OTP PROM is offered in a 32-pin, plastic leaded chip carrier package using 1,25-mm (50-mil) lead spacing (FM suffix). The TMS27PC010A is offered with two choices of temperature ranges, 0°C to 70°C (FML suffix) and – 40°C to 85°C (FME suffix). See Table 1.

EPROM AND OTP PROM	SUFFIX FOR OPERATING FREE- AIR TEMPERATURE RANGES					
	0°C to 70°C	– 40°C to 85°C				
TMS27C010A-xxx	JL	JE				
TMS27PC010A-xxx	FML	FME				

Table 1. Temperature Range Suffixes

These EPROMs and OTP PROMs operate from a single 5-V supply (in the read mode), thus are ideal for use in microprocessor-based systems. One other 13-V supply is needed for programming. All programming signals are TTL level. These devices are programmable using the SNAP! Pulse programming algorithm. The SNAP! Pulse programming algorithm uses a V_{PP} of 13 V and a V_{CC} of 6.5 V for a nominal programming time of thirteen seconds. For programming outside the system, existing EPROM programmers can be used. Locations can be programmed singly, in blocks, or at random.

operation

The seven modes of operation are listed in Table 2. The read mode requires a single 5-V supply. All inputs are TTL level except for V_{PP} during programming (13 V for SNAP! Pulse), and 12 V on A9 for signature mode.

MODE† **FUNCTION OUTPUT PROGRAM** READ **STANDBY PROGRAMMING VERIFY** SIGNATURE MODE **DISABLE INHIBIT** E V_{IH} V_{II} ٧_{II} V_{IH} ٧II V_{II} ٧_{II} G V_{IL} ۷ін Χ ۷ін VII Χ V_{IL} PGM Χ Χ Χ Χ Χ V_{IL} V_{IH} V_{PP} V_{PP} **VCC** VCC **VCC** Vpp V_{PP} **VCC** Vcc Vcc Vcc Vcc Vcc Vcc Vcc **VCC** V_H‡ V_H‡ A9 Χ Χ Χ Χ Χ Χ A0 Х Χ Χ Χ Χ Χ V_{IL} ۷ін CODE **DEVICE** DQ0-DQ7 Data Out Hi-Z Hi-Z Data In Data Out Hi-Z MFG

Table 2. Operation Modes

[†] X can be V_{IL} or V_{IH}.





97

D6

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read/output disable

When the outputs of two or more TMS27C010As or TMS27PC010As are connected in parallel on the same bus, the output of any particular device in the circuit can be read with no interference from competing outputs of the other devices. To read the output of a single device, a low-level signal is applied to the \overline{E} and \overline{G} pins. All other devices in the circuit should have their outputs disabled by applying a high level signal to one of these pins.

latchup immunity

Latchup immunity on the TMS27C010A and TMS27PC010A is a minimum of 250 mA on all inputs and outputs. This feature provides latchup immunity beyond any potential transients at the P.C. board level when the devices are interfaced to industry standard TTL or MOS logic devices. The input/output layout approach controls latchup without compromising performance or packing density.

power down

Active I_{CC} supply current can be reduced from 30 mA to 500 μ A by applying a high TTL input on \overline{E} and to 100 μ A by applying a high CMOS input on \overline{E} . In this mode all outputs are in the high-impedance state.

erasure (TMS27C010A)

Before programmig, the TMS27C010A EPROM is erased by exposing the chip through the transparent lid to a high intensity UV light (wavelength 2537 Å). The recommended minimum exposure dose (UV intensity × exposure time) is 15-W·s/cm². A typical 12-mW/cm², filterless UV lamp erases the device in 21 minutes. The lamp should be located about 2.5 cm above the chip during erasure. After erasure, all bits are in the high state. Normal ambient light contains the correct wavelength for erasure, therefore, when using the TMS27C010A, the window must be covered with an opaque label. After erasure (all bits in logic high state), logic lows are programmed into the desired locations. A programmed low can be erased only by UV light.

initializing (TMS27PC010A)

The one-time programmable TMS27PC010A PROM is provided with all bits in the logic high state, then logic lows are programmed into the desired locations. Logic lows programmed into an OTP PROM cannot be erased.

SNAP! Pulse programming

The TMS27C010A and TMS27PC010A are programmed using the TI SNAP! Pulse programming algorithm illustrated by the flowchart in Figure 1, which programs in a nominal time of thirteen seconds. Actual programming time varies as a function of the programmer used.

The SNAP! Pulse programming algorithm uses an initial pulse of 100 microseconds (μ s) followed by a byte verification to determine when the addressed byte has been successfully programmed. Up to 10 (ten) 100- μ s pulses per byte are provided before a failure is recognized.

The programming mode is achieved when $V_{PP} = 13 \text{ V}$, $V_{CC} = 6.5 \text{ V}$, $\overline{E} = V_{IL}$, $\overline{G} = \underline{V_{IH}}$. Data is presented in parallel (eight bits) on pins DQ0 through DQ7. Once addresses and data are stable, \overline{PGM} is pulsed low.

More than one device can be programmed when the devices are connected in parallel. Locations can be programmed in any order. When the SNAP! Pulse programming routine is complete, all bits are verified with $V_{CC} = V_{PP} = 5 \text{ V} \pm 10\%$.

program inhibit

Programming can be inhibited by maintaining a high level input on the \overline{E} or \overline{PGM} pins.

program verify

Programmed bits can be verified with $V_{PP} = 13 \text{ V}$ when $\overline{G} = V_{IL}$, $\overline{E} = V_{IL}$, and $\overline{PGM} = V_{IH}$.



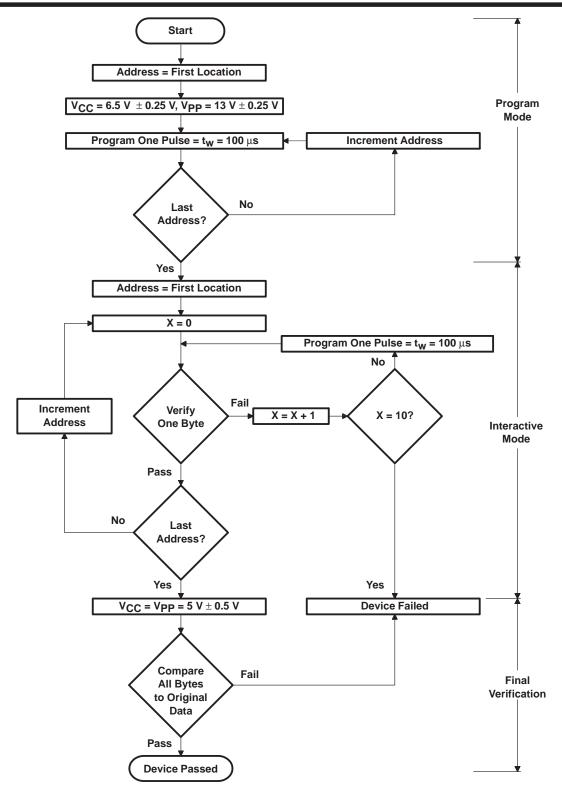


Figure 1. SNAP! Pulse Programming Flowchart



signature mode

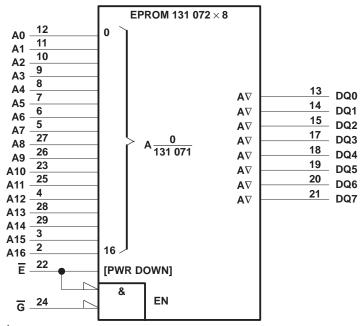
The signature mode provides access to a binary code identifying the manufacturer and type. This mode is activated when A9 (pin 26) is forced to 12 V. Two identifier bytes are accessed by toggling A0. All other addresses must be held low. The signature code for these devices is 97D6. A0 low selects the manufacturer's code 97 (Hex), and A0 high selects the device code D6 (Hex), as shown in Table 3.

Table 3. Signature Mode

IDENTIFIER [†]					PII	NS				
	A0	DQ7	DQ6	DQ5	DQ4	DQ3	DQ2	DQ1	DQ0	HEX
MANUFACTURER CODE	VIL	1	0	0	1	0	1	1	1	97
DEVICE CODE	VIH	1	1	0	1	0	1	1	0	D6

 $[\]overline{+E} = \overline{G} = V_{IL}$, A1-A8 = V_{IL}, A9 = V_H, A10-A16 = V_{IL}, V_{PP} = V_{CC}.

logic symbol‡



[‡]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. J package illustrated.



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absolute maximum ratings over operating free-air temperature rang	ge (unless otherwise noted)†
Supply voltage range, V _{CC} (see Note 1)	0.6 V to 7 V
Supply voltage range, VPP	
Input voltage range, All inputs except A9	0.6 V to V _{CC} + 1 V
A9	0.6 V to 13.5 V
Output voltage range, with respect to V _{SS} (see Note 1)	0.6 V to V _{CC} + 1 V
Operating free-air temperature range ('27C010A- JL,	
² 27PC010A- FML)	0°C to 70°C
Operating free-air temperature range ('27C010A- JE,	
² 27PC010A- FME)	– 40°C to 85°C
Storage temperature range, T _{sta}	65°C to 150°C

NOTE 1: All voltage values are with respect to GND.

recommended operating conditions

				'27C0 '27C0	10A/PC0	010A-12 010A-15	UNIT
				MIN	NOM	MAX	1
\/	Supply	Read mode (see Note 2)		4.5	5	5.5	V
Vcc	voltage	SNAP! Pulse programming a	algorithm	6.25	6.5	CO10A-20 M MAX 5 5.5 5 6.75 C VCC+0.6	V
\/	Supply	Read mode (see Note 3)		VCC−0.6	Vcc	VCC+0.6	V
VPP	voltage	SNAP! Pulse programming a	algorithm	12.75	13	13.25	V
\/	High loved de	a innut valtage	TTL	2		V _{CC} +0.5	V
VIH	nign-ievei do	c input voltage	CMOS	V _{CC} −0.2		V _{CC} +0.5	l v
V	l our lovel de	input voltage	TTL	- 0.5		0.8	V
VIL	Low-level do	input voltage	CMOS	- 0.5	5 5.5 6.5 6.75 VCC VCC+0.6 13 13.25 VCC+0.5 VCC+0.5 0.8 GND+0.2	l ^v	
TA	Operating free-air temperature		'27C010AJL '27PC010AFML	0		70	°C
TA	Operating fre	ee-air temperature	'27C010AJE '27PC010AFME	- 40		85	°C

NOTES: 2. V_{CC} must be applied before or at the same time as V_{PP} and removed after or at the same time as V_{PP}. The device must not be inserted into or removed from the board when VPP or VCC is applied.

3. During programming, Vpp must be maintained at 13 V \pm 0.25 V.



[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature

	PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT
Va	High level de output voltage		I _{OH} = -20 μA	V _{CC} -0.2		V
VOH	High-level dc output voltage		$I_{OH} = -2.5 \text{ mA}$	3.5		V
Va.	Low-level dc output voltage		$I_{OL} = 2.1 \text{ mA}$		0.4	V
VOL	Low-level dc output voltage		I _{OL} = 20 μA		0.1	V
l _l	Input current (leakage)		$V_{I} = 0 \ V \text{ to } 5.5 \ V$		±1	μΑ
IO	Output current (leakage)		$V_O = 0 V \text{ to } V_{CC}$		±1	μΑ
I _{PP1}	Vpp supply current		Vpp = V _{CC} = 5.5 V		10	μΑ
I _{PP2}	Vpp supply current (during program pu	se)	Vpp = 13 V		50	mA
laa.	Varanting and the standing	TTL-input level	$V_{CC} = 5.5 \text{ V}, \qquad \overline{E} = V_{IH}$		500	
ICC1	ACC subbit carrent (standay)	/CC supply current (standby) CMOS-input level	$V_{CC} = 5.5 \text{ V}, \qquad \overline{E} = V_{CC} \pm 0.2 \text{ V}$		100	μΑ
I _{CC2}	V _{CC} supply current (active) (output ope	n)	V_{CC} = 5.5 V, $E = V_{IL}$ t_{cycle} = minimum cycle time [†] , outputs open		30	mA

[†] Minimum cycle time = maximum access time.

capacitance over recommended ranges of supply voltage and operating free-air temperature, $f=1\ MHz^{\ddagger}$

	PARAMETER	TEST CONDITIONS	MIN	TYP§	MAX	UNIT
Cl	Input capacitance	$V_I = 0 V$, $f = 1 MHz$		4	8	pF
СО	Output capacitance	V _O = 0 V, f = 1 MHz		6	10	pF

[‡] Capacitance measurements are made on sample basis only.

switching characteristics over recommended ranges of operating conditions (see Notes 4 and 5)

PARAMETER		I TECT I		'27C010A-12 '27PC010A-12		'27C010A-15 '27PC010A-15		'27C010A-20 '27PC010A-20		UNIT	
		CONDITIONS	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
ta(A)	Access time from address			100		120		150		200	ns
t _{a(E)}	Access time from chip enable	CL = 100 pF, 1 Series 74		100		120		150		200	ns
ten(G)	Output enable time from G			55		55		75		75	ns
^t dis	Output disable time from \overline{G} or \overline{E} , whichever occurs first \P	TTL load, Input t _r ≤ 20 ns,	0	50	0	50	0	60	0	60	ns
t _V (A)	Output data valid time after change of address, \overline{E} , or \overline{G} , whichever occurs first¶	Input t _f ≤ 20 ns	0		0		0		0		ns

Value calculated from 0.5-V delta to measured output level.



[§] All typical values are at $T_A = 25^{\circ}C$ and nominal voltages.

NOTES: 4. For all switching characteristics the input pulse levels are 0.4 V to 2.4 V. Timing measurements are made at 2 V for logic high and 0.8 V for logic low (see Figure 2).

^{5.} Common test conditions apply for tdis except during programming.

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switching characteristics for programming: V_{CC} = 6.5 V and V_{PP} = 13 V (SNAP! Pulse), T_A = 25°C (see Note 4)

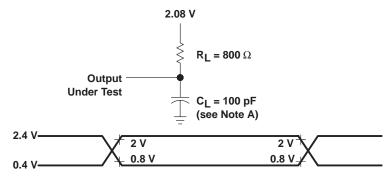
	PARAMETER —			UNIT
tdis(G)	Disable time, output disable time from \overline{G}	0	130	ns
ten(G)	Enable time, output enable time from \overline{G}		150	ns

NOTE 4: For all switching characteristics the input pulse levels are 0.4 V to 2.4 V. Timing measurements are made at 2 V for logic high and 0.8 V for logic low (see the ac testing waveform).

timing requirements for programming

			MIN	NOM	MAX	UNIT
tw(PGM)	Pulse duration, program	SNAP! Pulse programming algorithm	95	100	105	μs
t _{su(A)}	Setup time, address		2			μs
t _{su(E)}	Setup time, E		2			μs
t _{su(G)}	Setup time, G		2			μs
t _{su(D)}	Setup time, data		2			μs
t _{su(VPP)}	Setup time, V _{PP}		2			μs
t _{su(VCC)}	Setup time, V _{CC}		2			μs
th(A)	Hold time, address		0		, and the second	μs
th(D)	Hold time, data		2		·	μs

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and fixture capacitance.

B. The ac testing inputs are driven at 2.4 V for logic high and 0.4 V for logic low. Timing measurements are made at 2 V for logic high and 0.8 V for logic low for both inputs and outputs.

Figure 2. The ac Test Output Load Circuit and Waveform

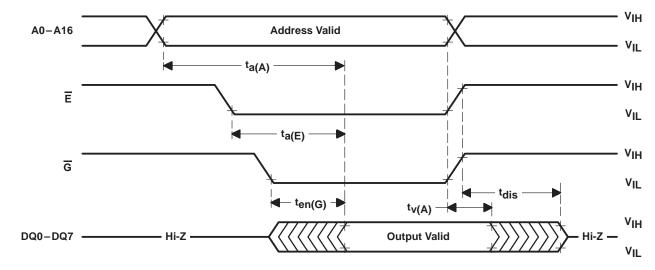
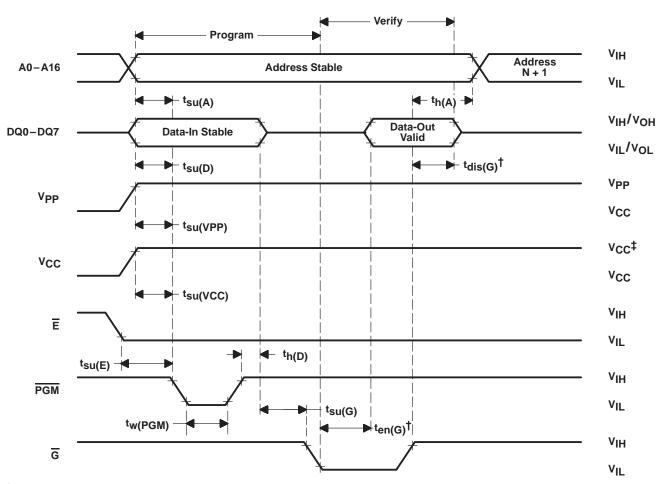


Figure 3. Read-Cycle Timing

PROGRAMMING INFORMATION



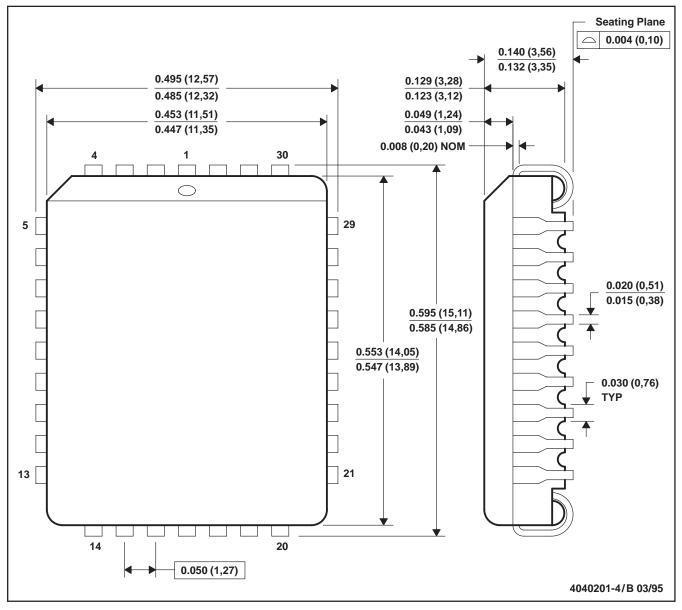
 $[\]dagger$ $t_{dis(G)}$ and $t_{en(G)}$ are characteristics of the device but must be accommodated by the programmer.

Figure 4. Program-Cycle Timing (SNAP! Pulse Programming)

^{‡13-}V VPP and 6.5-V VCC for SNAP! Pulse programming.

FM (R-PQCC-J32)

PLASTIC J-LEADED CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

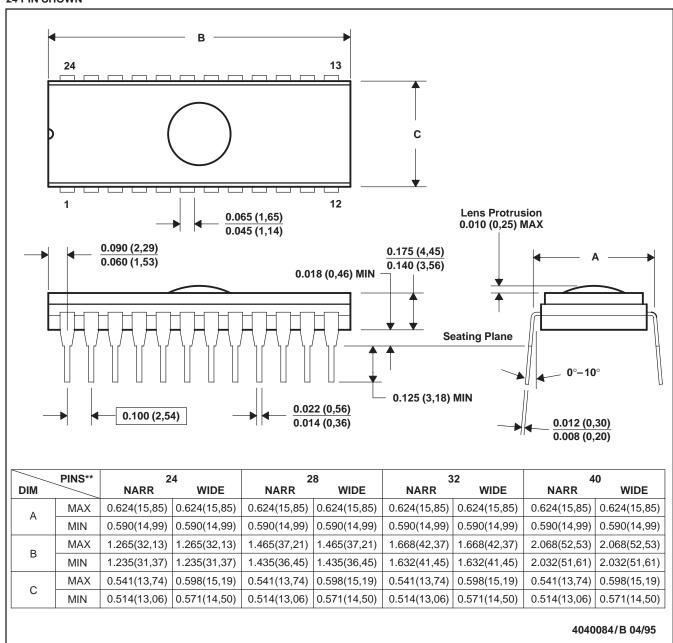
B. This drawing is subject to change without notice.

C. Falls within JEDEC MS-016

J (R-CDIP-T**)

CERAMIC SIDE-BRAZE DUAL-IN-LINE PACKAGE

24 PIN SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.



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